

SPW0442HR5H-1 Rev G Datasheet

### SPW0442HR5H-1

# Precision Top Port SiSonic<sup>TM</sup> Microphone

The SPW0442HR5H-1 is a miniature, high-performance, low power, top port silicon microphone. Using Knowles' proven high-performance SiSonic<sup>TM</sup> MEMS technology, the SPW0442HR5H-1 consists of an acoustic sensor, a low noise input buffer, and an output amplifier. These devices are suitable for applications such as cellphones, smart phones, laptop computers, sensors, digital still cameras, portable music recorders, and other portable electronic devices where excellent wideband audio performance and RF immunity are required.

### **Product Features**

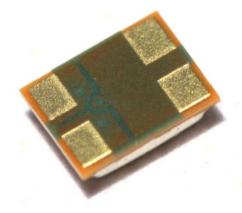
- Matched Sensitivity
- Small Package
- Low Current
- MaxRF Protection

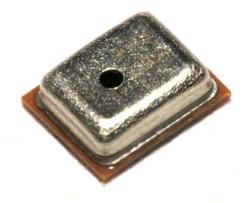
- Top Ported Design
- Ultra-Stable Performance
- Standard SMD Reflow
- Omnidirectional
- LGA Package

# **Typical Applications**

- Portable electronics
- Cellphones
- Laptop Computers

- Tablets
- Digital Still Cameras
- Portable Music Recorders





### **Absolute Maximum Ratings**

Table 1: Absolute Maximum Ratings

| Parameter                | Absolute Maximum Rating | Units |
|--------------------------|-------------------------|-------|
| Vdd to Ground            | -0.5, +5.0              | V     |
| OUTPUT to Ground         | -0.3, Vdd+0.3           | V     |
| Input Current to any pin | ±5                      | mA    |
| Storage Temperature      | -40 to +100             | °C    |
| Operating Temperature    | -30 to +100             | °C    |

Stresses exceeding these "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation at these or any other conditions beyond those indicated under "Acoustic & Electrical Specifications" is not implied. Exposure beyond those indicated under "Acoustic & Electrical Specifications" for extended periods may affect device reliability.

### **Acoustic & Electrical Specifications**

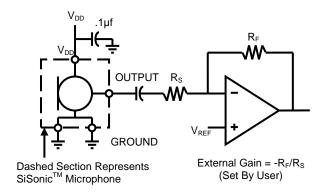
Table 2: Normal Mode Microphone Specifications

Test Conditions: 23 ±2°C. 55±20% R.H., Vdd(min) < Vdd < Vdd(max), no load, unless otherwise indicated

| Parameter                    | Symbol | Conditions  | Min | Тур       | Max           | Units  |
|------------------------------|--------|---|-----|-----------|---------------|--------|
| Supply Voltage               | Vdd    |   | 1.5 | -         | 3.6           | V      |
| Supply Current               | ldd    | Vdd = 1.8V  | -   | 130       | 165           | μA     |
| Supply Current <sup>1</sup>  | ldd    | Vdd = 3.6V  | -   | 150       | 185           | μA     |
| Sensitivity <sup>1</sup>     | S      | 94 dB SPL @ 1 kHz   | -43 | -42       | -41           | dBV/Pa |
| Signal to Noise Ratio        | SNR    | 94 dB SPL @ 1 kHz, A-weighted                                   | -   | 59        | -             | dB(A)  |
| Total Harmonic<br>Distortion | THD    | 94 dB SPL @ 1 kHz,<br>S = Typ, Rload > 3kΩ                      | -   | 0.15      | 0.25          | %      |
| Acoustic Overload Point      | AOP    | 10% THD @ 1 kHz,<br>S = Typ, Vdd = 3.6V, Rload > $3$ k $\Omega$ | 128 | 130       | ı             | dB SPL |
| Power Supply Rejection Ratio | PSRR   | 200 mVpp sine wave 50-20kHz<br>@1kHz, Vdd = 1.8V                | -   | 66        | 1             | dB     |
| Power Supply Rejection       | PSR    | 100 mVpp square wave  | -   | -100      | 1             | dBV(A) |
| DC Output                    |        | Vdd = 1.5V  | -   | 1.3       | -             | V      |
| Output Impedance             | Zout   | @ 1 kHz   | -   | -         | 500           | Ω      |
| Directivity                  |        |   |     | Omnic     | directional   |        |
| Polarity                     |        | Increasing sound pressure                                       |     | ecreasing | output voltag | ge     |

<sup>100%</sup> tested.

### **Application Notes**



Notes: All Ground pins must be connected to ground.

Capacitors near the microphone should not contain Class 2 dielectrics due to their piezoelectric effects.

Detailed information on acoustic, mechanical, and system integration can be found in the latest  $SiSonic^{TM}$  Design Guide application note.

Figure 1: Typical Application Circuit

### **Performance Curves**

Test Conditions: Vdd=1.8V, no load, unless otherwise indicated

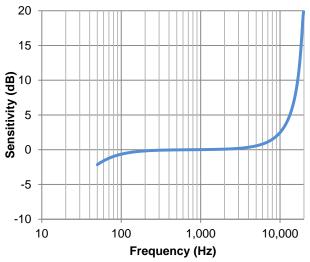


Figure 2: Typical Free Field Response Normalized to 1 kHz

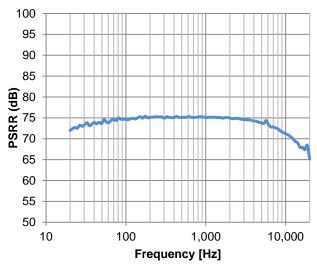


Figure 3: Typical PSRR

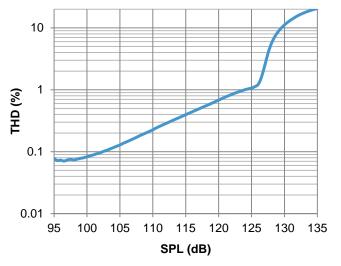


Figure 4: Typical THD vs SPL

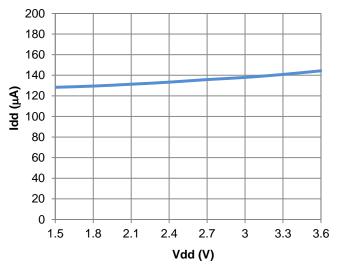
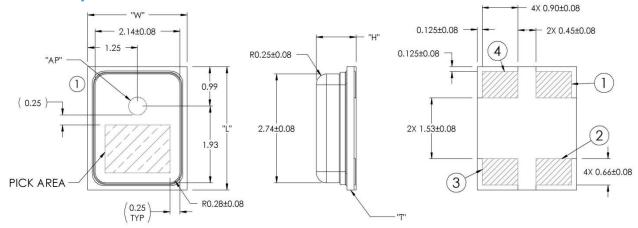


Figure 5: Typical Idd vs Vdd

# **Mechanical Specifications**



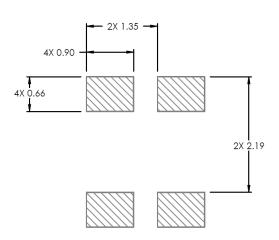
| Item               | Dimension | Tolerance      |
|--------------------|-----------|----------------|
| Length (L)         | 3.10      | ±0.10          |
| Width (W)          | 2.50      | ±0.10          |
| Height (H)         | 1.00      | ±0.10          |
| Acoustic Port (AP) | Ø0.45     | ±0.05          |
| PCB Thickness (T)  | 0.28      | +0.05<br>-0.03 |

| Pin# | Pin Name | Туре   | Description   |
|------|----------|--------|---------------|
| 1    | OUTPUT   | Signal | Output Signal |
| 2    | GROUND   | Power  | Ground        |
| 3    | GROUND   | Power  | Ground        |
| 4    | Vdd      | Power  | Power Supply  |

### **Example Land Pattern**

# 4X 0.90 4X 0.66 1 2X 2.19

### **Example Solder Stencil Pattern**



Notes:

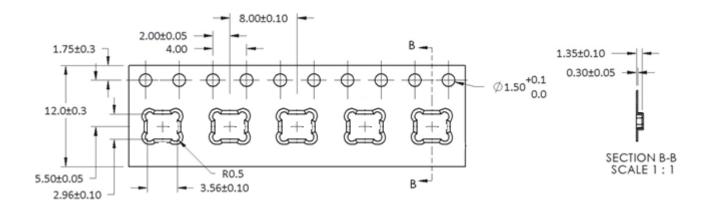
Pick Area only extends to 0.25 mm of any edge or hole unless otherwise specified.

Dimensions are in millimeters unless otherwise specified.

Tolerance is ±0.15mm unless otherwise specified

Detailed information on AP size considerations can be found in the latest *SiSonic*<sup>TM</sup> *Design Guide* application note. Further optimizations based on application should be performed.

## **Packaging & Marking Detail**



| Model Number  | Suffix | Reel Diameter | Quantity Per Reel |
|---------------|--------|---------------|-------------------|
| SPW0442HR5H-1 | -7     | 13"           | 5,700             |

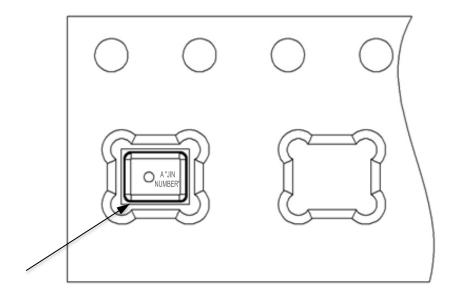
### Alpha Character A:

"S": Knowles SiSonic™ Production "E": Knowles Engineering Samples

"P": Knowles Prototype Samples

### "JIN Number":

Unique Job Identification Number For product traceability



Dimensions are in millimeters Notes:

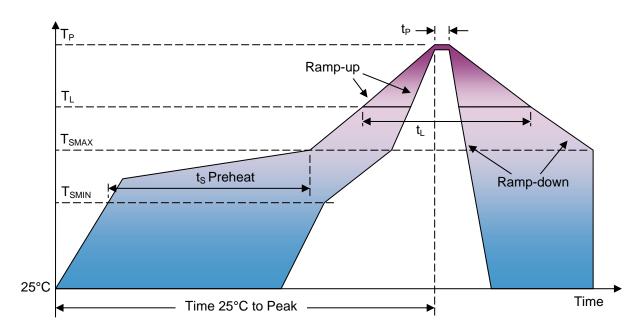
Vacuum pickup only in the pick Tape & reel per EIA-481 Rev C.

vise specified. Pin 1

ed in Mechanical Specifications.

Labels applied directly to reel and external package. Shelf life: Twelve (12) months when devices are to be stored in factory supplied, unopened ESD moisture sensitive bag under maximum environmental conditions of 30°C, 70% R.H.

### **Recommended Reflow Profile**



| Profile Feature   | Pb-Free         |  |
|---|-----------------|--|
| Average Ramp-up rate (T <sub>SMAX</sub> to T <sub>P</sub> )                     | 3°C/second max. |  |
| Preheat   |                 |  |
| Temperature Min (T <sub>SMIN</sub> )  | 150°C           |  |
| Temperature Max (T <sub>SMAX</sub> )  | 200°C           |  |
| <ul> <li>Time (T<sub>SMIN</sub> to T<sub>SMAX</sub>) (t<sub>S</sub>)</li> </ul> | 60-180 seconds  |  |
| Time maintained above:  |                 |  |
| <ul> <li>Temperature (T<sub>L</sub>)</li> </ul>                                 | 217°C           |  |
| Time (t <sub>L</sub> )  | 60-150 seconds  |  |
| Peak Temperature (T <sub>P</sub> )  | 260°C           |  |
| Time within 5°C of actual Peak Temperature (t <sub>P</sub> )                    | 20-40 seconds   |  |
| Ramp-down rate (T <sub>P</sub> to T <sub>SMAX</sub> )                           | 6°C/second max  |  |
| Time 25°C to Peak Temperature   | 8 minutes max   |  |

Notes: Based on IPC/JDEC J-STD-020 Revision C.

All temperatures refer to topside of the package, measured on the package body surface

### **Additional Notes**

- (A) MSL (moisture sensitivity level) Class 1.
- (B) Maximum of 3 reflow cycles is recommended.
- (C) In order to minimize device damage:
  - Do not board wash or clean after the reflow process.
  - Do not brush board with or without solvents after the reflow process.
  - Do not directly expose to ultrasonic processing, welding, or cleaning.
  - Do not insert any object in port hole of device at any time.
  - Do not apply over 30 psi of air pressure into the port hole.
  - Do not pull a vacuum over port hole of the microphone.
  - Do not apply a vacuum when repacking into sealed bags at a rate faster than 0.5 atm/sec.

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### **Materials Statement**

Meets the requirements of the European RoHS directive 2011/65/EC as amended.

Meets the requirements of the industry standard IEC 61249-2-21:2003 for halogenated substances and Knowles Green Materials Standards Policy section on Halogen-Free.

Product is Beryllium Free according to limits specified on the Knowles Hazardous Material List (HSL for Products).

Ozone depleting substances are not used in the product or the processes used to make the product, including compounds listed in Annex A, B, and C of the "Montreal Protocol on Substances That Deplete the Ozone Layer."

### **Reliability Specifications**

| Test                      | Description  |
|---------------------------|--|
| Thermal Shock             | 100 cycles of air-air thermal shock from -40°C to +125°C with 15 minute soaks (IEC 68-2-4)                     |
| High Temperature Storage  | +105°C environment for 1,000 hours (IEC 68-2-2 Test Ba)  |
| Low Temperature Storage   | -40°C environment for 1,000 hours (IEC 68-2-1 Test Aa)   |
| High Temperature Bias     | +105°C environment while under bias for 1,000 hours (IEC 68-2-2 Test Ba)                                       |
| Low Temperature Bias      | -40°C environment while under bias for 1,000 hours (IEC 68-2-1 Test Aa)  |
| Temperature/Humidity Bias | +85°C/85% R.H. environment while under bias for 1,000 hours (JESD22-A101A-B)                                   |
| Vibration                 | 12 minutes in each X, Y, Z axis from 20 to 2,000 Hz with peak acceleration of 20 G (MIL 883E, Method 2007.2,A) |
| ESD-HBM                   | 3 discharges of ±2kV direct contact to I/O pins (MIL 883E, Method 3015.7)                                      |
| ESD-HBM (LID/GND)         | 3 discharges of ±8kV direct contact to lid while unit is grounded (MIL 883E, Method 3015.7)                    |
| ESD-MM                    | 3 discharges of ±200V direct contact to IO pins (ESD STM5.2)   |
| Reflow                    | 5 reflow cycles with peak temperature of +260°C  |
| Mechanical Shock          | 3 pulses of 10,000 G in each of the ±X, ±Y, and ±Z directions (IEC 68-2-27 Test Ea)                            |

Notes: After 3 reflow cycles, the sensitivity of the microphones shall not deviate more than 1 dB from its initial value.